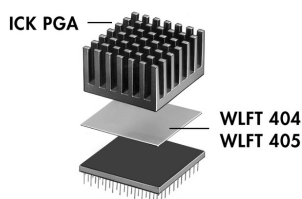


Data sheet Product ICK PGA 9 x 9



Heatsinks and active heatsinks for processors>Heatsinks for PGA
 24.2 x 24.2 x 12.3 mm, for IC design PGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	24.2 mm
height:	12.3 mm
plate thickness:	3.5 mm
length:	24.2 mm
thermal resistance:	14 - 3.3 K/W
dissipation loss:	3 W
surface:	black anodised

Technical Drawing

